

01/10/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10043468	01/10/2002	438		2823	

**APPLICANTS: Farnworth Warren;

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A CON OF 09/478,386 01/06/2000
WHICH IS A DIV OF 09/304,368 05/04/1999 PAT 6,204,095
WHICH IS A CON OF 09/056,124 04/06/1998 PAT 5,933,713

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** FOREIGN APPLICATIONS VERIFIED:

PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO	
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	3085.4US (96-1033.4)	
Verified and Acknowledged Examiners's initials		
TITLE : Method of forming overmolded chip scale package and resulting product		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner PREPARED FOR ISSUE Application Examiner	
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